

**Dr. Athinodoros Klipfel** Head of Sales

# Submillimeter Resolution Pavement Scans at up to 100 km/h

C6 Series

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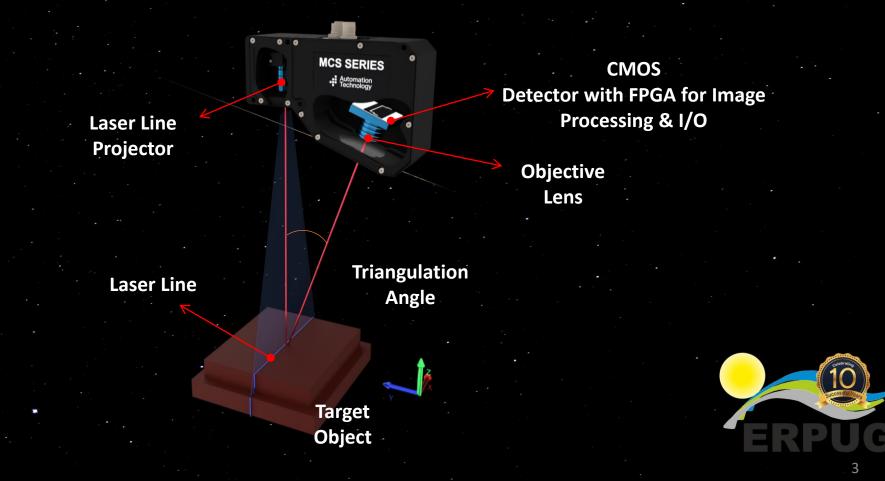
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- The profile scan principle of Laser triangulation
- Requirements and technology limitations for high-speed submillimeter pavement scans
- WARP: A new technology pushing the speed limits of laser triangulaton
- Additional functions for high speed pavement scans
- Application examples of submillimeter resolution pavement scans



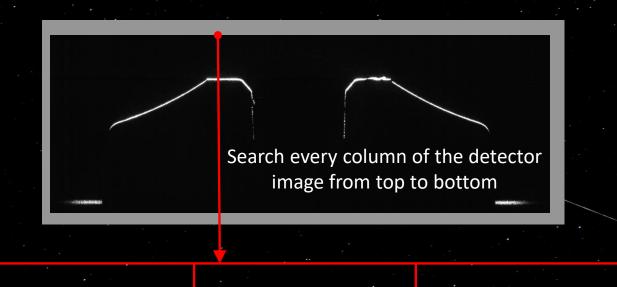


### The Profile Scan Principle of Laser Triangulation



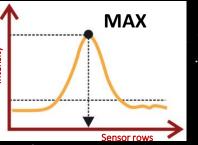


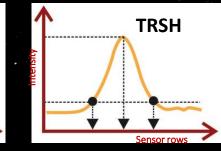
#### The Profile Scan Principle of Laser Triangulation

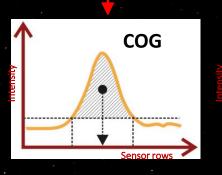


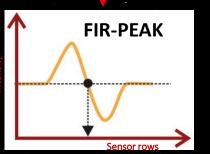
#### **Profile Extraction Algorithms**

- MAX: find the maximum intensity peak position
- THRSH: threshold the Gauss reflection and find its average position
- COG: calculate the Center of Gravity of intensity peak position
- FIR-PEAK: calculate the first derivative (steepness) of the Gauss reflection and find the zero crossing position











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### REQUIREMENTS

 Pavement scans with resolution < 1mm at high travel speed require high-speed 3D laser profiling technology, e.g. for 0.5mm resolution at 100 km/h the profile speed must be at least 56 kHz





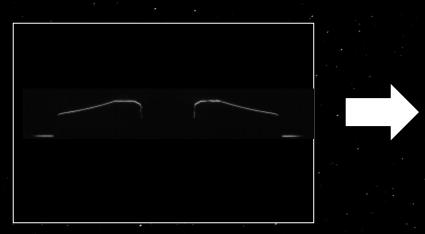
#### LIMITATIONS

Existing Laser triangulation technology is based on transfer of CMOS detector image to FPGA for processing and height profile extraction

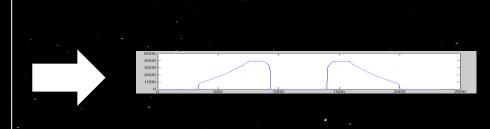
#### **CMOS Detector**

#### FPGA

#### **Height Profile Output**



### Profile Extraction Algorithms

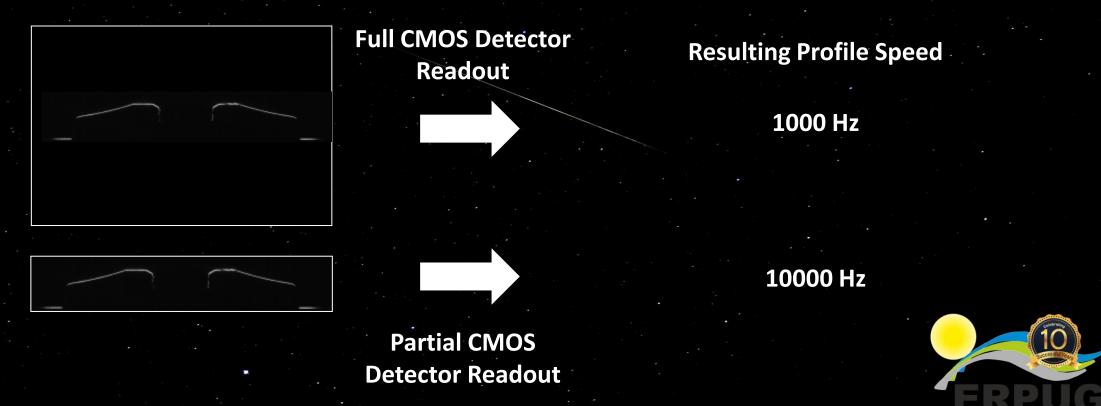






#### LIMITATIONS

The profile speed depends on the number of pixels readout of the CMOS detector and transferred to the FPGA for processing. Example:



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#### LIMITATIONS

The CMOS detector region to be readout depends on the target surface geometry.

- For flat target objects and surfaces a detector region with small height may be readout resulting to high profile speed. However, this can work reliably only under the following conditions:
  - the target surface remains flat (no curvature)
  - the target surface profile remains aligned to the detector (no skew)
  - the distance between target surface and the detector remains constant



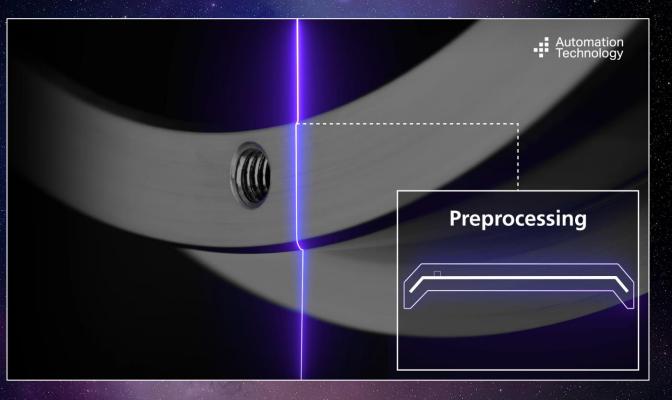
High speed pavement scans are not feasible as these conditions <u>cannot</u> be met in practice





Widely Advanced Rapid Profiling (WARP)

- Integrated pre-processing on CMOS imager
- On-sensor detection of the laser line profile
- Profile speed is boosted up to 200 kHz @ 3K resolution (3072 pixels per line)



### NEW TECHNOLOGY FOR LASER TRIANGULATION!

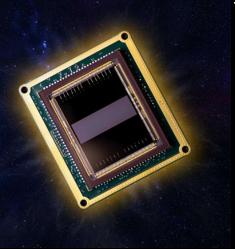


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Widely Advanced Rapid Profiling (WARP)

For every column of the detector image only a small part **around the position of laser line reflection** is transferred to the FPGA for further processing

The image readout follows the laser profile like a sleeve.

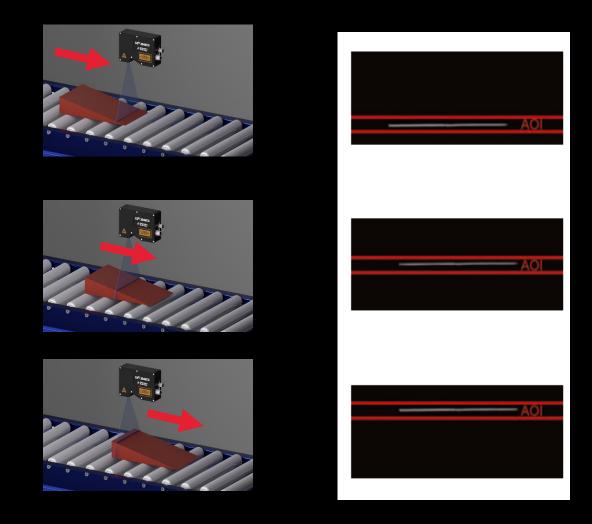








Widely Advanced Rapid Profiling (WARP) combined with Region Tracking



The position of readout region is automatically updated to track the line position in the detector image, when the distance from the target surface is changing during travel.

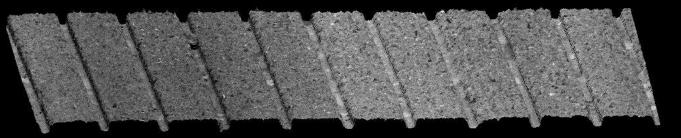




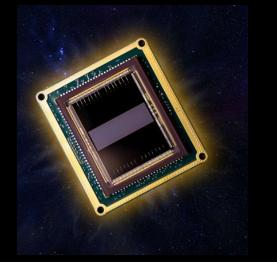
Advantages of Widely Advanced Rapid Profiling (WARP)

High profile speed independent of the:

- Target surface shape
- Target surface profile alignment to the detector
- Target surface distance to the detector (with the help of Region Tracking)
- Target surface color and reflectivity



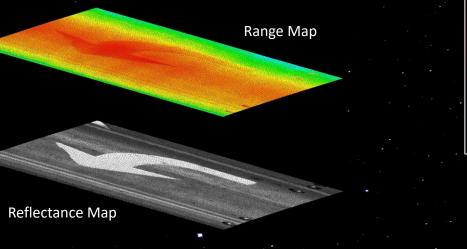


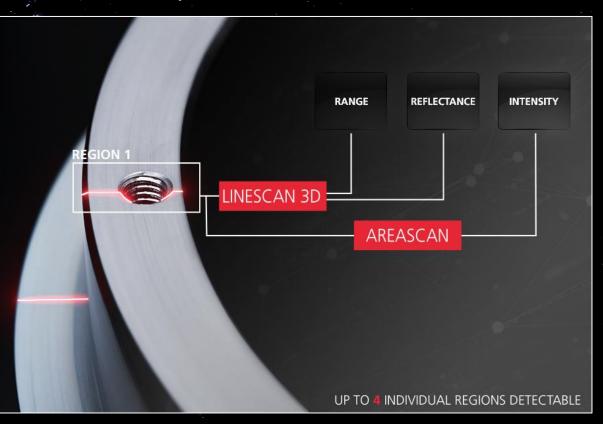


#### **Additional Functions:**

#### MULTIPART

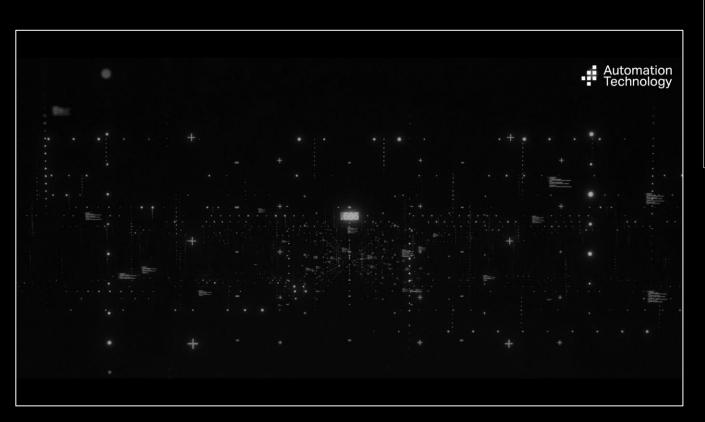
- Simultaneous output of up to 10 different features
- Allows additional output of reflectance or scatter data.







#### **Additional Functions:**



#### MULTIPEAK

- Detection of up to four different peaks
- Helps to reduce laser interference and secondary reflections on shiny surfaces (e.g. metals)
- Improves the scan quaity on transparent / translucent surfaces (e.g. glass, plastics)





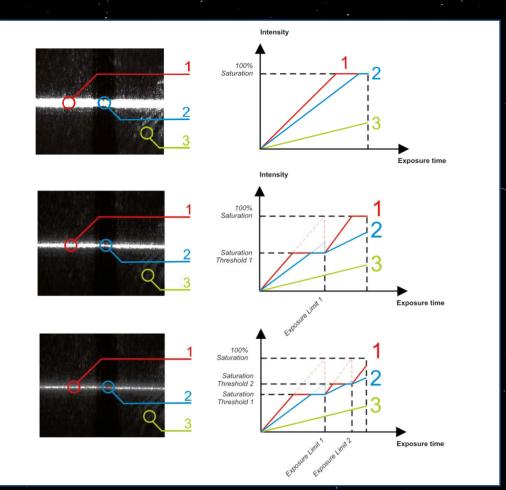
Sensor Image with secondary laser reflection

Profile data of secondary laser reflection are output separately





#### **Additional Functions:**



#### MULTISLOPE

- Increase dynamic range of sensor up to 90dB
- Prevents sensor intensity saturation for precise laser detection
- Allows to scan any parts from white to black and from dull to shiny without intensity saturation
- No need to adjust the exposure time or laser power when the part reflecitivity changes

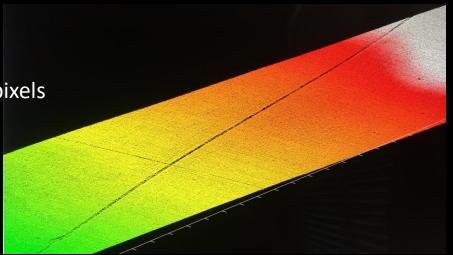
#### Optimized Image Quality – No Saturation

Applications of Widely Advanced Rapid Profiling (WARP) on

**Pavement Scanning** 

#### Example #1

- Travel Speed 100 km/h
- Scan width 3m (2 cameras with X-FOV 1.5 m each)
- WARP imager C6-3070-WARP profile speed: 58 kHz @ Region 3072 x 102 pixels
- Resolution X and Y: 0.5 mm
- Triangulation angle: 15°
- Resolution Z: 0.03 mm (with 6 subpixels)
- Z-Range without Region Tracking: ca. 0.2 m
- Z-Range with Region Tracking: up to ca. 2 m depend. on LASER DOF





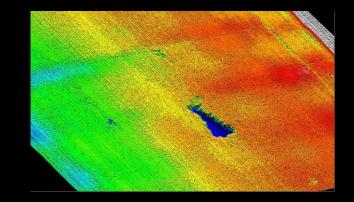


Applications of Widely Advanced Rapid Profiling (WARP) on

**Pavement Scanning** 

#### Example #2

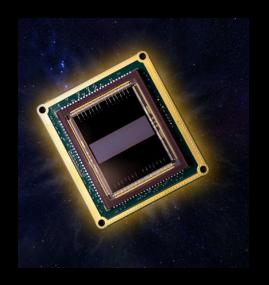
- Travel Speed 100 km/h
- Scan width 4m (2 cameras with X-FOV 2 m each)
- WARP imager C6-3070-WARP profile speed: 40 kHz @ Region 3072 x 156 pixels
- Resolution X and Y: 0.7 mm
- Triangulation angle: 15°
- Resolution Z: 0.04 mm (with 6 subpixels)
- Z-Range without Region Tracking: ca. 0.4 mm
- Z-Range with Region Tracking: up to ca. 3 m depend. on LASER DOF







#### SUMMARY



- The Widely Advanced Rapid Profiling technology (WARP) enables the scanning of road pavement with submillimeter resolution at travel speed up to 100 km/h.
- The unprecedented combination of 3072 points per profile with a profile speed up to 200kHz generates high density 3D point clouds enabling a precise and reliable analysis of cracks, ruts, and texture of the road surface.
- WARP is a revolutionary technology contributing to an improved 3D pavement analysis.





## THANK YOU! QUESTIONS?

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Note: the 3D pavement scans, and vehicle picture shown in the presentation are courtesy of HyMIT LLC 19